ASCOLUTION CONNECTING ELECTRONICS INDUSTRIES international and Pa	<b>Dosition De</b> IPC, Bannock In-American d	e <b>claration</b> burn, Illinois. A copyright conve	Il rights reserved ntions.	under both									if the item is an as r has engineering	
	IPC Web Site for Information on IPC-1752 Standard Form Type   http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
upplier Information														
Company name* Company unique ID			ique ID		Unique ID Authority				Response Date*					
onsemi											2024-04-26			
ontact Name	Title - Conta	- Contact			Phone - Contact*				Email - Contact*					
Product-Env-Stewards Pr			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative			sentative		Phone - Representative* Email - Representative*									
roduct-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Requester Item Number Mfr Iter		n Number Mfr Item Name			Effective Da	ate Ve	ersion	Manufacturing Site		W	veight*	UOM	Unit Type	
	MT9P0 DR1	19P031I12STM- 5 MP 1/3 CIS				2024-04-26 MY5			259.0 mg		mg	Each		
Ianufacturing Proccess Informa	ntion										L L			
Terminal Plating / Grid Array M	Material Terminal Base Alloy		Alloy	J-STD-020 MS	SL Rating	Peak Pr	Process Body Temperature Max Time at Peak		ime at Peak	Temperature Number of Reflow Cycles		eles		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy	lloy 4			260	260 C		30 seco		second	seconds 3		
omments														
or more information regarding materia	l composition	n please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	HS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead ), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl halate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	59.5	mg		Misc.	proprietary data		0.2261	mg
			Supplier	Silicon (Si)	7440-21-3		58.6848	mg
			Supplier	Aluminum (Al)	7429-90-5		0.589	mg
Die Attach	2.2	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.825	mg
			Supplier	Ethylene Glycol	107-21-1		0.022	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.066	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.462	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.825	mg
Imaging Lens	55.3	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		2.765	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		2.765	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		2.765	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		2.765	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.2765	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.765	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		2.765	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		38.4335	mg
Lid Attach	2.4	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.7584	mg
			Supplier	Filler (SiO2)	68909-20-6		0.1248	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.7584	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.7584	mg
Mold Compound-Black	55.0	mg		Phenolic Resin	proprietary data		8.25	mg
			Supplier	Oxirane	39817-09-9		8.25	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.65	mg
			Supplier	Carbon Black (C)	1333-86-4		0.55	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		35.2	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.1	mg
Substrate and Solder Mask	84.3	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		17.8632	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		1.1043	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.2782	mg
			Supplier	Acetophenone Derivative	Proprietary Data		1.6523	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2782	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.2782	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2	8.194	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.3046	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	2.8325	mg
			Supplier	Copper (Cu)	7440-50-8	39.9666	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	8.548	mg
Wire Bond - Au	0.3	mg	Supplier	Gold (Au)	7440-57-5	0.3	mg